

## Glass Passivated Junction Rectifiers

### Reverse Voltage 50V to 1000V Forward Current 3.0 Amperes

# 1N5401G thru 1N5408G

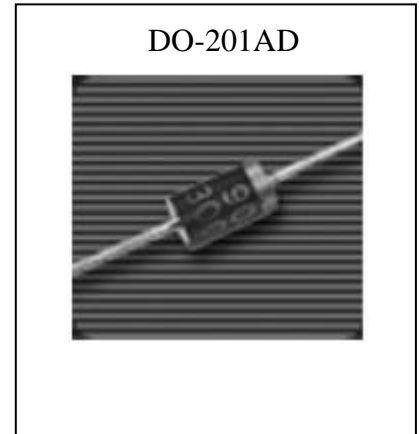
### Features

- Low forward voltage drop.
- High current capability
- High reliability
- High surge current capability

### Mechanical Data

- Case : Molded plastic DO-201AD
- Epoxy : UL94V-0 rate flame retardant
- Terminals: Axial leads, solderable per MIL-STD-202 method 208 guaranteed
- Polarity: Color band denotes cathode end.
- High temperature soldering guaranteed : 250°/10seconds, .375”(9.5mm) lead length at 5 lbs.(2.3kg) tension
- Weight: 0.042 ounce, 1.195 gram

### Outline



### Maximum Ratings and Electrical Characteristics

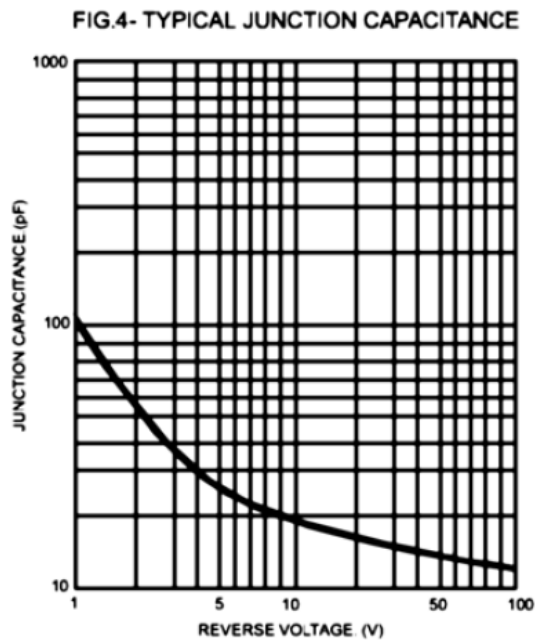
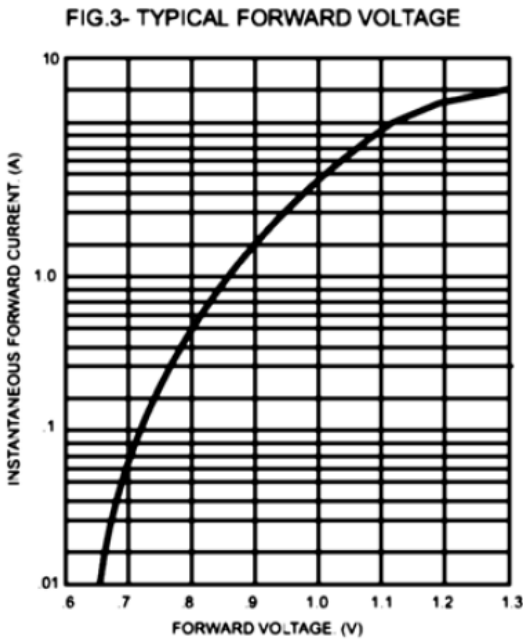
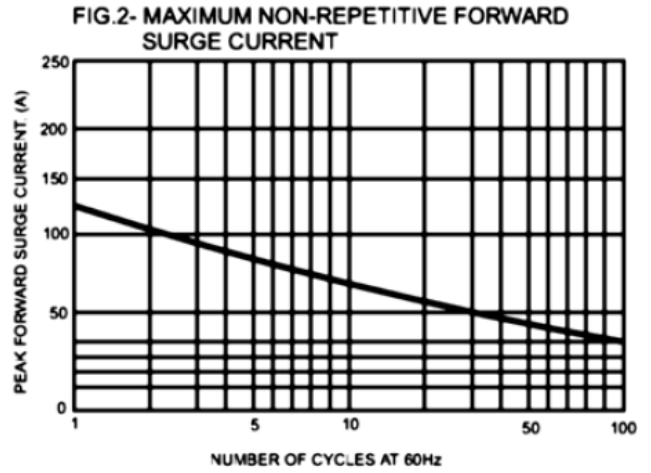
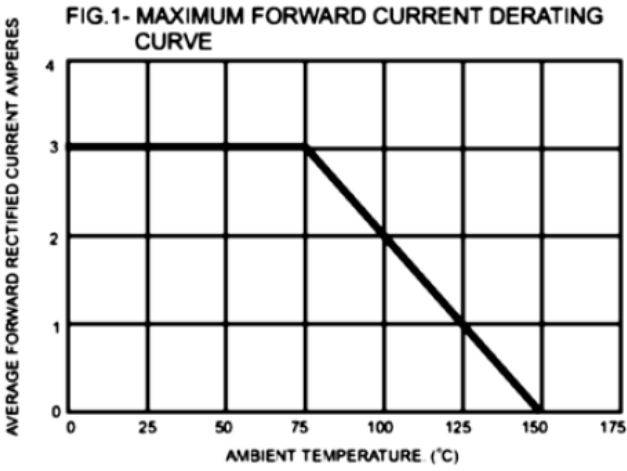
(Rating at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%)

Parameter	Symbol	Type							Units
		1N5400G	1N5401G	1N5402G	1N5404G	1N5406G	1N5407G	1N5408G	
Repetitive peak reverse voltage	V <sub>RRM</sub>	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V <sub>RMS</sub>	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V <sub>R</sub>	50	100	200	400	600	800	1000	V
Maximum instantaneous forward voltage, I <sub>F</sub> =3A	V <sub>F</sub>	1.1							V
Maximum average forward rectified current @ T <sub>A</sub> =75°C	I <sub>F(AV)</sub>	3							A
Peak forward surge current @8.3ms single half sine wave superimposed on rated load (JEDEC method)	I <sub>FSM</sub>	125							A
Maximum DC reverse current, at rated DC blocking voltage	I <sub>R</sub>	5							μA
		100							
Typical junction capacitance (Note 1)	C <sub>J</sub>	30							pF
Storage temperature	T <sub>stg</sub>	-55 ~ +150							°C
Operating junction temperature range	T <sub>J</sub>	-55 ~ +150							°C

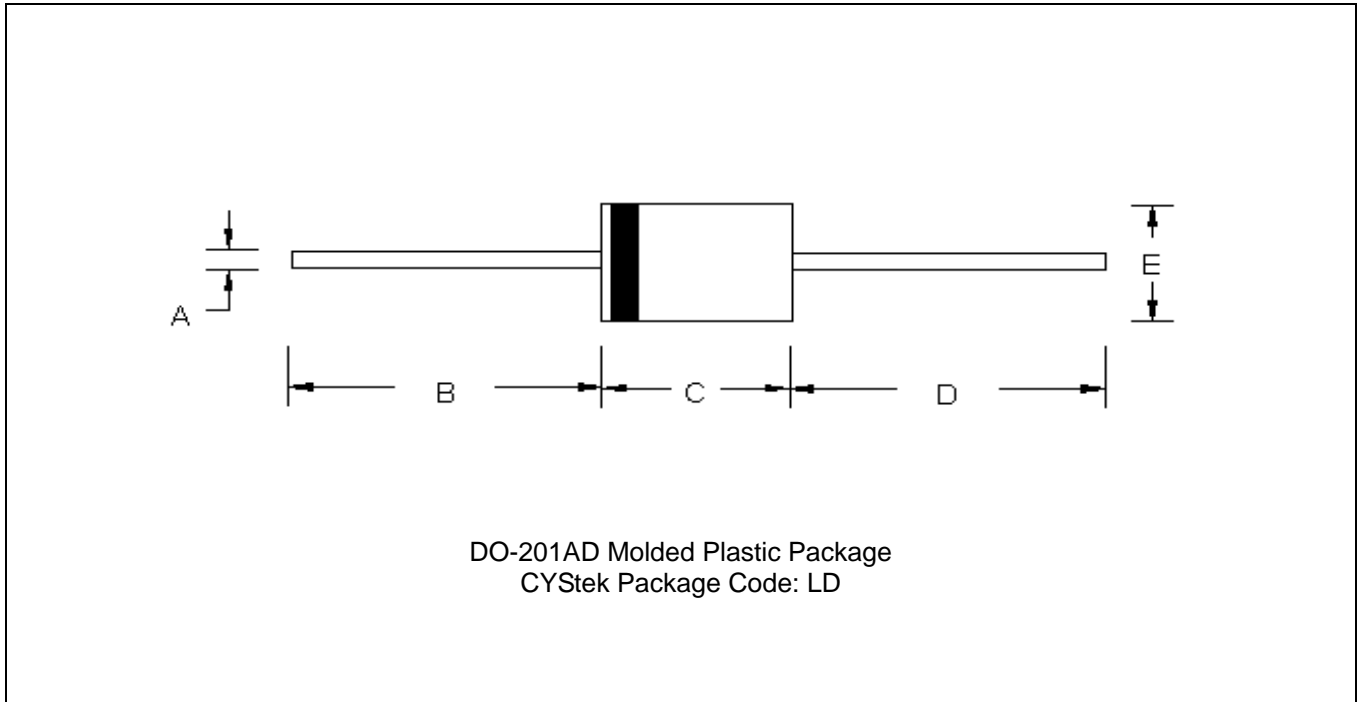
Note : 1.Measured at 1MHz and applied reverse voltage of 4 V<sub>DC</sub>



### Characteristic Curves



**DO-201AD Dimension**



DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	φ0.048	φ0.052	φ1.20	φ1.30	D	1.000	-	25.40	-
B	1.000	-	25.40	-	E	φ0.190	φ0.220	φ4.80	φ5.60
C	0.285	0.375	7.20	9.50					

**Notes :** 1.Controlling dimension : millimeters.  
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.  
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

**Material :**

- Lead : Axial leads, solderable per MIL-STD-750, Method 2026 guaranteed.
- Mold Compound : Epoxy resin family, flammability solid burning class: UL94V-0

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